

Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	11900
Number of Logic Elements/Cells	31500
Total RAM Bits	1381376
Number of I/O	144
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 125°C (TJ)
Package / Case	324-LFBGA
Supplier Device Package	324-UBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgxfc3b6u15a7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Summary of Cyclone V Features

Summary of Features for Cyclone V Devices Table 2.

Feature		Description			
Technology	TSMC's 28-nm low-p 1.1 V core voltage				
Packaging	 Wirebond low-halogen packages Multiple device densities with compatible package footprints for seamless migration between different device densities RoHS-compliant and leaded⁽¹⁾options 				
High-performance FPGA fabric	Enhanced 8-input ALM v	vith four registers			
Internal memory blocks	•	(b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory			
Embedded Hard IP blocks	Variable-precision DSP • Native support for up to three signal processing precision level (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the sar variable-precision DSP block • 64-bit accumulator and cascade • Embedded internal coefficient memory • Preadder/subtractor for improved efficiency				
	Memory controller DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support				
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port			
Clock networks		ol clock network d peripheral clock networks are not used can be powered down to reduce dynamic power			
Phase-locked loops (PLLs)	Precision clock synthInteger mode and from	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode			
FPGA General-purpose I/Os (GPIOs)	400 MHz/800 Mbps 6 On-chip termination	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength			
Low-power high-speed serial interface	Transmit pre-emphase	Sbps integrated transceiver speed sis and receiver equalization infiguration of individual channels			
HPS (Cyclone V SE, SX, and ST devices only)	 Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I²C interface, and up to 85 HPS GPIO interfaces 				
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers ot ROM			
	·	continued			

⁽¹⁾ Contact Intel for availability.



Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight™ JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing (2) Partial reconfiguration (3)

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel® sales representatives.



Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

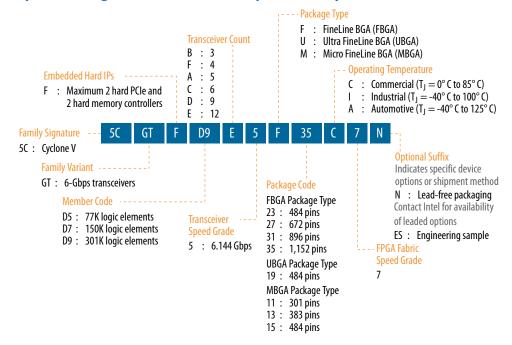
Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource			Member Code					
		A2	A4	A5	A7	А9		
Logic Elements	(LE) (K)	25	49	77	150	301		
ALM		9,430	18,480	29,080	56,480	113,560		
Register		37,736	73,920	116,320	225,920	454,240		
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200		
	MLAB	196	303	424	836	1,717		
Variable-precision	on DSP Block	25	66	150	156	342		
18 x 18 Multipli	er	50	132	300	312	684		
PLL		4	4	6	7	8		
GPIO		224	224	240	480	480		
LVDS	Transmitter	56	56	60	120	120		
	Receiver	56	56	60	120	120		
Hard Memory C	ontroller	1	1	2	2	2		



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code				
		D5	D7	D9			
Logic Elements (LE) (K)		77	150	301			
ALM		29,080	56,480	113,560			
Register		116,320	225,920	454,240			
Memory (Kb)	M10K	4,460	6,860	12,200			
	MLAB	424	836	1,717			
Variable-precision DS	P Block	150	156	342			
18 x 18 Multiplier		300	312	684			
PLL			7	8			
6 Gbps Transceiver		6	9	12			
GPIO ⁽⁵⁾		336	480	560			
LVDS	Transmitter	84	120	140			
	,	•		continued			

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

CV-51001 | 2018.05.07



Resource		Member Code				
		D5	D7	D9		
	Receiver	84	120	140		
PCIe Hard IP Block		2	2	2		
Hard Memory Controller		2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 9. Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver ≤ 5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	M3 (11 i		M3 (13 i		M484 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	_	_	224	6
D7	_	_	_	_	240	3	240	6
D9	_	_	_	_	_	_	240	5

Member Code	F48 (23 I		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	240	6	336	6	_	_	_	_
D7	240	6	336	9 (6)	480	9 (6)	_	_
D9	224	6	336	9 (6)	480	12 ⁽⁷⁾	560	12 ⁽⁷⁾

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽⁶⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

⁽⁷⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Cyclone V SE

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Maximum Resources

Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resource		Member Code					
		C2	C4	C5	C6		
Logic Elements (LE) (K)		25	40	85	110		
ALM		9,430	15,880	32,070	41,910		
Register		37,736	60,376	128,300	166,036		
Memory (Kb)	M10K	1,400	2,700	3,970	5,570		
	MLAB	138	231	480	621		
Variable-precision [DSP Block	36	84	87	112		
18 x 18 Multiplier		72	168	174	224		
FPGA PLL		5	5	6	6		
continued							



Resource		Member Code					
		C2	C4	C5	C6		
HPS PLL		3	3	3	3		
3 Gbps Transceiver		6	6	9	9		
FPGA GPIO (8)	FPGA GPIO ⁽⁸⁾		145	288	288		
HPS I/O	HPS I/O		181	181	181		
LVDS	Transmitter	32	32	72	72		
	Receiver	37	37	72	72		
PCIe Hard IP Block		2	2	2 (9)	2 (9)		
FPGA Hard Memory	FPGA Hard Memory Controller		1	1	1		
HPS Hard Memory Controller		1	1	1	1		
Arm Cortex-A9 MP0	Core Processor	Dual-core	Dual-core	Dual-core	Dual-core		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 13. Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

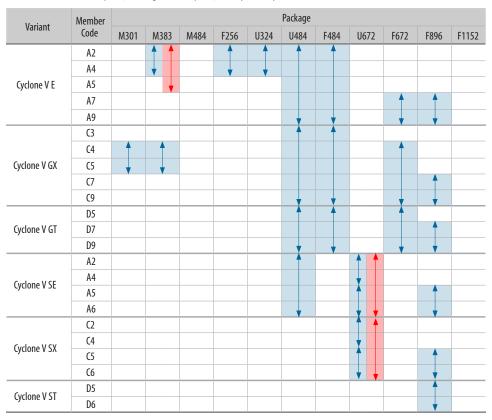
^{(9) 1} PCIe Hard IP Block in U672 package.



I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note:

To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 \times 9, two 18 \times 18, or one 27 \times 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable- precision DSP Block		dent Input and plications Ope		18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder
	DSP BIOCK	DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



Variant	Member Code	Variable- precision	Independent Input and Output Multiplications Operator			18 x 18 Multiplier	18 x 18 Multiplier
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Cyclone V Devices

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Mombor	Member M10		ML	AB	Total RAM Bit
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



	Member	M1	.0К	ML	.AB	- Total RAM Bit
Variant		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

Embedded Memory Configurations

Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	×1

Clock Networks and PLL Clock Sources

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note:

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- \bullet LVDS output buffer with programmable differential output voltage (V $_{\text{OD}}$) and programmable pre-emphasis
- ullet On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Fre	Minimum Frequency	
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	Custom PHY IP core with preset feature GbE transmitter synchronization state machine	Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	,		continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

⁽¹³⁾ XAUI is supported through the soft PCS.

 $^{^{(14)}}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	Custom PHY IP core with preset feature Electrical idle	Custom PHY IP core with preset feature Signal detect Wider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	Dedicated deterministic latency PHY IP core	Dedicated deterministic latency PHY IP core
OBSAI RP3	0.768 to 3.072	Transmitter (TX) manual bit-slip mode	Receiver (RX) deterministic latency state machine
V-by-One HS	Up to 3.75	Custom PHY IP core	Custom PHY IP core
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		Wider spread of asynchronous SSC

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

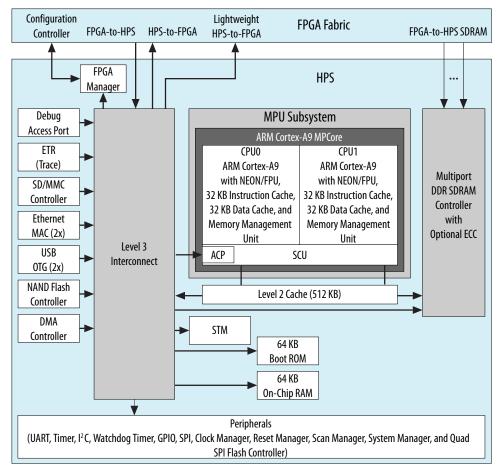
The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.



Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.

CV-51001 | 2018.05.07



Note:

Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks[®], and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note:

The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	 Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams. Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	 Added descriptions to package plan tables for Cyclone V GT and ST devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.12	 Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. Updated logic elements (LE) (K) for the following devices: Cyclone V E A7: Updated from 149.5 to 150 Cyclone V GX C3: Updated from 35.5 to 36 Cyclone V GX C7: Updated from 149.7 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: Cyclone V GX C3: Updated from 291 to 182 Cyclone V GX C4: Updated from 678 to 424 Cyclone V GX C5: Updated from 1,338 to 836 Cyclone V GX C9: Updated from 2,748 to 1,717
		continued



Date	Version	Changes
		 Updated MLAB RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 181 to 182 Cyclone V GX C4: Updated from 295 to 424 Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 1,531 to 1,532 Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 472 to 678 Cyclone V GX C5: Updated from 679 to 678
March 2015	2015.03.31	Added internal scrubbing feature under configuration in Summary of Features for Cyclone V Devices table. Added optional suffix "SC: Internal scrubbing support" to the following diagrams: — Sample Ordering Code and Available Options for Cyclone V E Devices — Sample Ordering Code and Available Options for Cyclone V GX Devices — Sample Ordering Code and Available Options for Cyclone V SE Devices — Sample Ordering Code and Available Options for Cyclone V SX Devices
January 2015	2015.01.23	 Updated Sample Ordering Code and Available Options for Cyclone V ST Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade. Operating Temperature: Removed C and A temperature grades FPGA Fabric Speed Grade: Removed -6 and -8 speed grades Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: Device Variants for the Cyclone V Device Family table Sample Ordering Code and Available Options for Cyclone V ST Devices figure Maximum Resource Counts for Cyclone V ST Devices Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. Logic elements (LE) (K): Updated from 35.7 to 35.5 Variable-precision DSP block: Updated from 51 to 57 18 x 18 multiplier: Updated from 102 to 114 Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. Variableprecision DSP Block: Updated from 51 to 57 9 x 9 Multiplier: Updated from 153 to 171 18 x 18 Multiplier: Updated from 102 to 114 27 x 27 Multiplier: Updated from 51 to 57 18 x 18 Multiplier Adder Mode: Updated from 51 to 57 18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 19 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 M10 yeared Embedded Memory Capacity and Distribution in Cyclone V Devices table for Cyclone V GX G3 devices. M10K RAM bit (Kb): Updated from 1,190 to 1,350 MLAB Block: Updated from 255 to 291 MLAB RAM bit (Kb): Updated from 1,349 to 1,531
October 2014	2014.10.06	Added a footnote to the "Transceiver PCS Features for Cyclone V Devices" table to show that PCIe Gen2 is supported for Cyclone V GT and ST devices.
continued		